

SANYO Semiconductors DATA SHEET

LC87F1JJ2A — FROM 192K byte, RAM 16384 byte on-chip

CMOSIC

8-bit 1-chip Microcontroller with USB-host controller

Overview

The LC87F1JJ2A is an 8-bit microcomputer that, centered around a CPU running at a minimum bus cycle time of 83.3ns, integrates on a single chip a number of hardware features such as 192K-byte flash ROM (onboard programmable), 16384-byte RAM, an on-chip debugger, a sophisticated 16-bit timer/counter (may be divided into 8-bit timers), a 16-bit timer (may be divided into 8-bit timers or PWMs), four 8-bit timers with a prescaler, a base timer serving as a realtime clock, 3 channels of synchronous SIO interface with automatic data transfer capabilities, an asynchronous/synchronous SIO interface, a UART interface (full duplex), a full-speed USB interface (host control function), an 8-bit 12-channel AD converter, 2 channels of 12-bit PWM, a system clock frequency divider, an infrared remote control receiver circuit, and a 41-source 10-vector interrupt feature.

Features

- ■Flash ROM
 - Capable of on-board programming with a wide range of supply voltages: 3.0 to 5.5V
 - Block-erasable in 128 byte units
 - Writes data in 2-byte units
 - 196608 × 8 bits

■RAM

- 16384×9 bits
- ■Bus Cycle Time
 - 83.3ns (When CF=12MHz)

Note: The bus cycle time here refers to the ROM read speed.

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- ■Minimum Instruction Cycle Time (tCYC)
 - 250ns (When CF=12MHz)

■Ports

• I/O ports

Ports whose I/O direction can be designated in 1-bit units 28 (P10 to P17, P20 to P27, P30 to P34,

P70 to P73, PWM0, PWM1, XT2)

Ports whose I/O direction can be designated in 4-bit units 8 (P00 to P07)

USB ports
 Dedicated oscillator ports
 2 (UHD+, UHD-)
 2 (CF1, CF2)

Input-only port (also used for oscillation)
 Reset pin
 1 (XT1)
 RES)

• Power supply pins 6 (VSS1 to VSS3, VDD1 to VDD3)

■Timers

• Timer 0: 16-bit timer/counter with 2 capture registers.

Mode 0: 8-bit timer with an 8-bit programmable prescaler (with two 8-bit capture registers) × 2 channels

Mode 1: 8-bit timer with an 8-bit programmable prescaler (with two 8-bit capture registers)

+ 8-bit counter (with two 8-bit capture registers)

Mode 2: 16-bit timer with an 8-bit programmable prescaler (with two 16-bit capture registers)

Mode 3: 16-bit counter (with two 16-bit capture registers)

• Timer 1: 16-bit timer/counter that supports PWM/toggle outputs

Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs) + 8-bit timer/

counter with an 8-bit prescaler (with toggle outputs)

Mode 1: 8-bit PWM with an 8-bit prescaler × 2 channels

Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs)

(toggle outputs also possible from lower-order 8 bits)

Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs)

(lower-order 8 bits may be used as PWM outputs)

- Timer 4: 8-bit timer with a 6-bit prescaler
- Timer 5: 8-bit timer with a 6-bit prescaler
- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Base timer
 - 1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.
 - 2) Interrupts programmable in 5 different time schemes

■SIO

- SIO0: Synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Transfer clock cycle: 4/3 to 512/3 tCYC
 - 3) Automatic continuous data transmission (1 to 256 bits, specifiable in 1-bit units) (Suspension and resumption of data transmission possible in 1 byte units)
- SIO1: 8-bit asynchronous/synchronous serial interface
 - Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)
 - Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)
 - Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)
 - Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)
- SIO4: Synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Transfer clock cycle: 4/3 to 1020/3 tCYC
 - 3) Automatic continuous data transmission (1 to 8192 bytes, specifiable in 1 byte units) (Suspension and resumption of data transmission possible in 1 byte units or in word units)
 - 4) Auto-start-on-falling-edge function
 - 5) Clock polarity selectable
 - 6) CRC16 calculator circuit built in

Continued from preceding page.

- SIO9: Synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Transfer clock cycle: 4/3 to 1020/3 tCYC
 - 3) Automatic continuous data transmission (1 to 8192 bytes, specifiable in 1 byte units) (Suspension and resumption of data transmission possible in 1 byte units or word units)
 - 4) Auto-start-on-falling-edge function
 - 5) Clock polarity selectable
 - 6) CRC16 calculator circuit built in

■Full Duplex UART

1) Data length: 7/8/9 bits selectable

2) Stop bits: 1 bit (2 bits in continuous transmission mode)

3) Baud rate: 16/3 to 8192/3 tCYC

■AD Converter: 8 bits × 12 channels

■PWM: Multifrequency 12-bit PWM × 2 channels

■Infrared Remote Control Receiver Circuit

- 1) Noise rejection function (noise filter time constant: Approx. 120µs when the 32.768kHz crystal oscillator is selected as the base clock)
- 2) Supports data encoding systems such as PPM (Pulse Position Modulation) and Manchester encoding.
- 3) X'tal HOLD mode release function

■USB Interface (host control function)

- 1) Compliant with full-speed (12M bps) specifications
- 2) Supports 4 transfer types (control transfer, bulk transfer, interrupt transfer, and isochronous transfer).

■Audio Interface

1) Sampling frequency (fs): 8kHz/11.025kHz/12kHz/16kHz/22.05kHz/24kHz/32kHz/44.1kHz/48kHz

2) Master clock frequency: 256fs/384fs
3) Bit clock selectable: 48fs/64fs
4) Data bit length: 16/18/20/24 bits

5) LSB first/MSB first mode selectable

6) Left-justification/right-justification/I2S format selectable

■Watchdog Timer

- Watchdog timer using external RC circuitry
- Interrupt and reset signals selectable

■Clock Output Function

- 1) Can output a clock with a clock rate of 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, or 1/64 of the source oscillator clock selected as the system clock.
- 2) Can output the source oscillation clock for the subclock.

■Interrupts

- 41 sources, 10 vector addresses
 - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
 - 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4/UHC bus active/remote control signal receive
4	0001BH	H or L	INT3/INT5/base timer
5	00023H	H or L	T0H/INT6/UHC device attach/UHC device detach/UHC resume
6	0002BH	H or L	T1L/T1H/INT7/SIO9/AIF start
7	00033H	H or L	SIO0/UART1 receive
8	0003BH	H or L	SIO1/SIO4/UART1 transmit/AIF end
9	00043H	H or L	ADC/T6/T7/UHC-ACK/UHC-NAK/UHC error/UHC-STALL
10	0004BH	H or L	Port 0/PWM0/PWM1/T4/T5/UHC-SOF/DMCOPY/AIF error

- Priority levels X > H > L
- Of interrupts of the same level, the one with the smallest vector address takes precedence.
- ■Subroutine Stack Levels: 8192 levels maximum (The stack is allocated in RAM.)
- ■High-speed Multiplication/Division Instructions

16 bits × 8 bits
24 bits × 16 bits
16 bits ÷ 8 bits
24 bits ÷ 16 bits
16 bits ÷ 8 bits
16 bits ÷ 16 bits
17 tCYC execution time
18 tCYC execution time
19 tCYC execution time
10 tCYC execution time
10 tCYC execution time
11 tCYC execution time
12 tCYC execution time
13 tCYC execution time
14 tCYC execution time
15 tCYC execution time
16 tCYC execution time
17 tCYC execution time
18 tCYC execution time
19 tCYC execution time
10 tCYC execution time

■Oscillation and PLL Circuits

RC oscillation circuit (internal): For system clock
 CF oscillation circuit: For system clock

• Crystal oscillation circuit: For system clock, and realtime clock

• PLL circuit (internal): For USB interface (see Fig.5) and audio interface (see Fig. 6)

■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
 - 1) Oscillation is not halted automatically.
 - 2) There are three ways of releasing the HALT mode.
 - (1) Setting the reset pin to the lower level.
 - (2) System resetting by watchdog timer
 - (3) Generating an interrupt
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
 - 1) The PLL base clock generator, CF, RC and crystal oscillators automatically stop operation.
 - 2) There are five ways of releasing the HOLD mode.
 - (1) Setting the reset pin to the lower level
 - (2) System resetting by watchdog timer
 - (3) Having an interrupt source established at one of the INT0, INT1, INT2, INT4, and INT5 pins * The INT0 and INT1 pins must be configured only for level detection.
 - (4) Having an interrupt source established at port 0
 - (5) Having an bus active interrupt source established in the USB host control circuit
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer.
 - 1) The PLL base clock generator, CF and RC oscillator automatically stop operation.
 - 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
 - 3) There are seven ways of releasing the X'tal HOLD mode.
 - (1) Setting the reset pin to the low level
 - (2) System resetting by watchdog timer
 - (3) Having an interrupt source established at one of the INT0, INT1, INT2, INT4, and INT5 pins * The INT0 and INT1 pins must be configured only for level detection.
 - (4) Having an interrupt source established at port 0
 - (5) Having an interrupt source established in the base timer circuit
 - (6) Having an bus active interrupt source established in the USB host control circuit
 - (7) Having an interrupt source established in the infrared remote controller receiver circuit

■Package Form

• SQFP48(7×7): Lead-/Halogen-free type

■Development Tools

• On-chip debugger: TCB87- type B + LC87F1JJ2A

■Flash ROM Programming Boards

Package	Programming board			
SQFP48(7×7)	W87F55256SQ			

■ Flash ROM Programmer

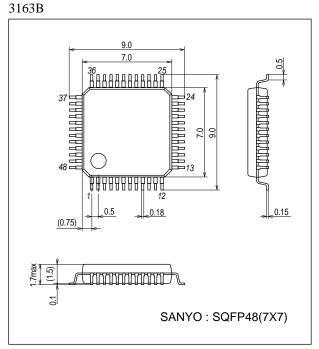
Maker		Model	Supported Version	Device	
Flash Support Group, Inc. (FSG)	Single	AF9708/ Single AF9709/AF9709B/AF9709C (including Ando Electric Co., Ltd. models)		LC87F1JJ2A	
Flash Support Group, Inc. (FSG)	Onboard	AF9101/AF9103(main unit) (FSG)	(Note 2)	LC87F1JJ2A	
+ SANYO(Note 1)	single/ganged	SIB87(interface driver) (SANYO)	(Note 2)		
CANDO	Single/ganged	SKK/SKK Type B (SANYO FWS)	Application version: 1.04 or later		
SANYO	Onboard single/ganged	SKK-DBG Type B (SANYO FWS)	Chip data version: 2.17 or later	LC87F1JJ2	

Note 1: PC-less standalone onboard programming is possible using the FSG onboard programmer (AF9101/AF9103) and the serial interface driver (SIB87) provided by SANYO in pair.

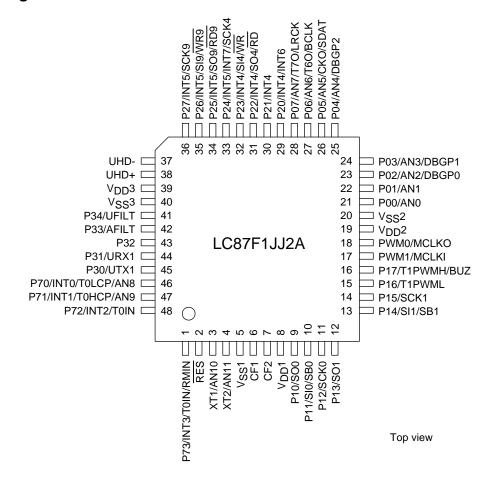
Note 2: Dedicated programming device and program are required depending on the programming conditions. Contact SANYO or FSG if you have any questions or difficulties regarding this matter.

Package Dimensions

unit: mm (typ)



Pin Assignment

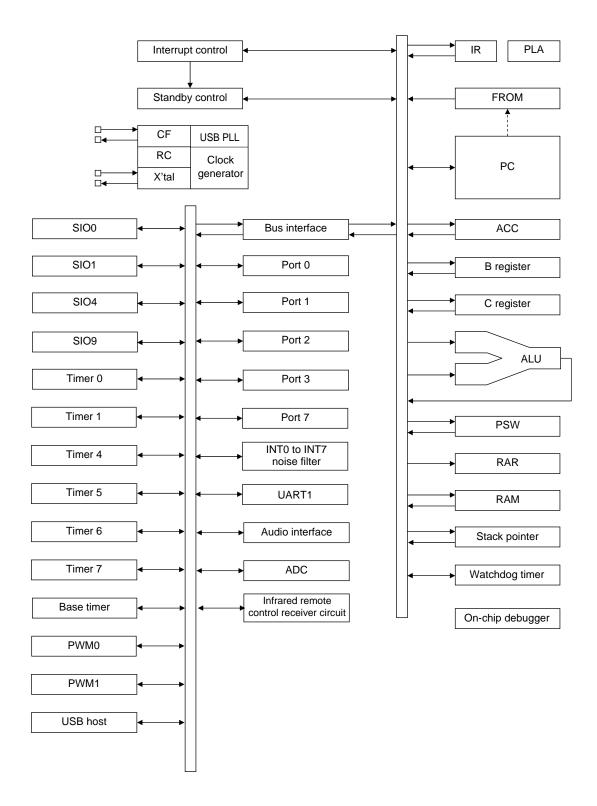


SANYO: SQFP48(7×7) "Lead-/Halogen-free type"

SQFP48	NAME
1	P73/INT3/T0IN/RMIN
2	RES
3	XT1/AN10
4	XT2/AN11
5	V _{SS} 1
6	CF1
7	CF2
8	V _{DD} 1
9	P10/SO0
10	P11/SI0/SB0
11	P12/SCK0
12	P13/SO1
13	P14/SI1/SB1
14	P15/SCK1
15	P16/T1PWML
16	P17/T1PWMH/BUZ
17	PWM1/MCLKI
18	PWM0/MCLKO
19	V _{DD} 2
20	V _{SS} 2
21	P00/AN0
22	P01/AN1
23	P02/AN2/DBGP0
24	P03/AN3/DBGP1

SQFP48	NAME
25	P04/AN4/DBGP2
26	P05/AN5/CKO/SDAT
27	P06/AN6/T6O/BCLK
28	P07/AN7/T7O/LRCK
29	P20/INT4/INT6
30	P21/INT4
31	P22/INT4/SO4/RD
32	P23/INT4/SI4/WR
33	P24/INT5/INT7/SCK4
34	P25/INT5/SO9/RD9
35	P26/INT5/SI9/WR9
36	P27/INT5/SCK9
37	UHD-
38	UHD+
39	V _{DD} 3
40	V _{SS} 3
41	P34/UFILT
42	P33/AFILT
43	P32
44	P31/URX1
45	P30/UTX1
46	P70/INT0/T0LCP/AN8
47	P71/INT1/T0HCP/AN9
48	P72/INT2/T0IN

System Block Diagram



Pin Description

Pin Name	I/O			De	scription			Option		
V _{SS} 1,V _{SS} 2,	-	- power supply						No		
V _{SS} 3 V _{DD} 1, V _{DD} 2	-	+ power supply	,					No		
V _{DD} 3	-		reference voltage							
Port 0	I/O	8-bit I/O ports								
P00 to P07	- "		bit I/O ports D specifiable in 4-bit units							
P00 t0 P07		*		ed on and off in 4	-bit units.					
		HOLD release			2.1. d					
		Port 0 interrup	•							
		Pin functions	·							
		AD converter	input ports: AN(to AN7(P00 to	P07)					
		On-chip debu	gger pins: DBG	P0 to DBGP2(P0)2 to P04)					
		P05: System	clock output/aud	dio interface SDA	AT input/output					
		P06: Timer 6	toggle output/au	idio interface BC	LK input/output					
		P07: Timer 7	toggle output/au	ıdio interface LR	CK input/output					
Port 1	I/O	8-bit I/O ports	;					Yes		
P10 to P17		I/O specifiable	e in 1-bit units							
		Pull-up resistor	ors can be turne	d on and off in 1	-bit units.					
		Pin functions								
		P10: SIO0 da	•		4։ SIO1 data iոթւ		ut			
			ta input/bus inpu	•	5: SIO1 clock inp	-				
			ck input/output		6: Timer 1 PWML	•				
.	1/0	P13: SIO1 da	· · · · · · · · · · · · · · · · · · ·	P1	7: Timer 1 PWMF	H output/beeper	output	.,		
Port 2	I/O	8-bit I/O ports						Yes		
P20 to P27		I/O specifiable in 1-bit units Pull-up resistors can be turned on and off in 1-bit units.								
		•	ors can be turne	on and oπ in 1	-bit units.					
		Pin functions P20 to P22: INT4 input/HOLD release input/timer 1 event input/timer 01 capture input/								
		P20 to P23: INT4 input/HOLD release input/timer 1 event input/timer 0L capture input/ timer 0H capture input								
		P24 to P27: INT5 input/HOLD release input/timer 1 event input/timer 0L capture input/								
		timer 0H capture input								
		P20: INT6 input/timer 0L capture 1 input								
		P22: SIO4 data input/output/parallel interface RD output								
		P23: SIO4 data input/output/parallel interface WR output								
		P24: SIO4 clock input/output/INT7 input/timer 0H capture 1 input								
		P25: SIO9 data input/output/parallel interface RD9 output								
		P26: SIO9 data input/output/parallel interface WR9 output								
		P27: SIO9 clock input/output								
		Interrupt ackn	owledge types	1	1	T				
			Rising	Falling	Rising & Falling	H level	L level			
		INT4	enable	enable	enable	disable	disable			
		INT5	enable	enable	enable	disable	disable			
		INT6	enable	enable	enable	disable	disable			
		INT7	enable	enable	enable	disable	disable			
Port 3	I/O	• 5-bit I/O ports	<u> </u>					Yes		
P30 to P34	1	I/O specifiable								
. 55 15 1 54		·		d on and off in 1	-bit units.					
		Pin functions								
		P30: UART1 1	ransmit							
		P31: UART1 i	receive							
		P33: Audio int	terface PLL filte	r circuit connecti	on pin (See Fig.	6.)				
		P34: USB inte	erface PLL filter	circuit connectio	n pin (See Fig. 5	.)		<u> </u>		

Continued from preceding page.

Pin Name	I/O			Des	cription			Option	
Port 7	I/O	• 4-bit I/O ports	4-bit I/O ports						
P70 to P73		• I/O specifiable in 1-bit units							
		Pull-up resistors can be turned on and off in 1-bit units. Divide the second of							
		Pin functions							
		*		•	apture input/wat	chdog timer outp	out		
		P71: INT1 input		-	-				
		•		•	ent input/timer 0	L capture input/			
			d clock counter i	•	avant innut/time	Oll conture inn	.4/		
		•	mote control red	,	event input/timer	on capture inpo	u/		
		AD converter in		•					
		Interrupt acknow		70), 71143(171)					
			Rising	Falling	Rising & Falling	H level	L level		
		INT0	enable	enable	disable	enable	enable		
		INT1	enable	enable	disable	enable	enable		
		INT2	enable	enable	enable	disable	disable		
		INT3	enable	enable	enable	disable	disable		
PWM0	I/O	PWM0, PWM1 o	utput ports					No	
PWM1		General-purpose input port							
		Pin functions							
		PWM0: Audio ir	nterface master	clock output					
		PWM1: Audio ir	nterface master	clock input					
UHD-	I/O	USB data I/O pin	UHD-/general-p	ourpose I/O por	t			No	
UHD+	I/O	USB data I/O pin	UHD+/general-	purpose I/O po	rt			No	
RES	I	Reset pin						No	
XT1	1	• 32.768kHz crys	tal oscillator inp	ut				No	
		Pin functions							
		General-purpos							
		AD converter in							
		Must be connec	ted to V _{DD} 1 wh	nen not to be us	sed.				
XT2	I/O	• 32.768kHz crys	tal oscillator out	tput				No	
		Pin functions							
		General-purpos							
		AD converter in							
054	<u>.</u>			on and kept ope	n if not to be use	ed.			
CF1	I	Ceramic/crystal r	esonator input					No	
CF2	0	Ceramic/crystal r	esonator output					No	

Port Output Types

The table below lists the types of port outputs and the presence/absence of a pull-up resistor.

Data can be read into any input port even if it is in the output mode.

Port Name	Option Selected in Units of	Option Type	Output Type	Pull-up Resistor	
P00 to P07	1 bit	1	CMOS	Programmable (Note 1)	
		2	Nch-open drain	No	
P10 to P17	1 bit	1	CMOS	Programmable	
P20 to P27 P30 to P34		2	Nch-open drain	Programmable	
P70	-	No	Nch-open drain	Programmable	
P71 to P73	-	No	CMOS	Programmable	
PWM0, PWM1	-	No	CMOS	No	
UHD+, UHD-	-	No	CMOS	No	
XT1	-	No	Input only	No	
XT2	-	No	32.768kHz crystal resonator output (Nch-open drain when in general-purpose output mode)	No	

Note 1: Programmable pull-up resistors for port 0 are controlled in 4 bit units (P00 to 03, P04 to 07).

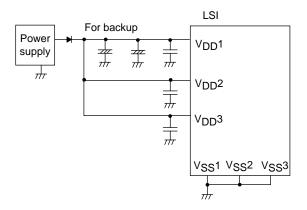
User Options

Option Name Type		Flash ROM Version	Option Selected in Units of	Setting
Port output type	D00 + D07		412	CMOS
	P00 to P07	0	1 bit	Nch-open drain
	P10 to P17		4 1.54	CMOS
	P10 to P17	0	1 bit	Nch-open drain
	D00 t- D07		4 1.4	CMOS
	P20 to P27	0	1 bit	Nch-open drain
	D20 to D24		4 1.4	CMOS
	P30 to P34	0	1 bit	Nch-open drain
Program start		0		00000h
address	-	0	-	1FE00h
USB Regulator	1100 0 11			Use
	USB Regulator	0	-	Nonuse
	USB Regulator			Use
	(at HOLD mode)	0	-	Nonuse
	USB Regulator	0		Use
	(at HALT mode)	0	-	Nonuse

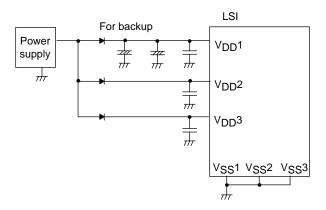
Power Pin Treatment

Connect the IC as shown below to minimize the noise input to the $V_{DD}1$ pin and extend the backup period. Be sure to electrically short the $V_{SS}1$, $V_{SS}2$, and $V_{SS}3$ pins.

Example 1: When the microcontroller is in the backup state in the HOLD mode, the power to sustain the high level of output ports is supplied by their backup capacitors.



Example 2: The high level output at ports is not sustained and unstable in the HOLD backup mode.



USB Reference Power Option

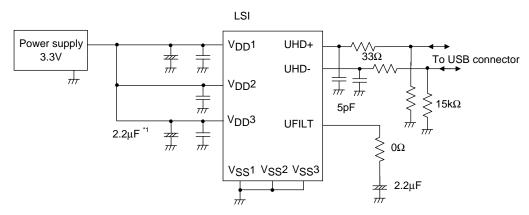
When a voltage 4.5 to 5.5V is supplied to V_{DD}1 and the internal USB reference voltage circuit is activated, the reference voltage for USB port output is generated. The active/inactive state of the reference voltage circuit can be switched by optional settings. The procedure for marking the optional settings is described below.

		(1)	(2)	(3)	(4)
Option settings	USB regulator	Use	Use	Use	Nonuse
	USB regulator in HOLD mode	Use	Nonuse	Nonuse	Nonuse
	USB regulator in HALT mode	Use	Nonuse	Use	Nonuse
Reference voltage circuit state	Normal mode	Active	Active	Active	Inactive
	HOLD mode	Active	Inactive	Inactive	Inactive
	HALT mode	Active	Inactive	Active	Inactive

- When the USB reference voltage circuit is made inactive, the level of the reference voltage for USB port output is equal to V_{DD}1.
- Selection (2) or (3) can be used to set the reference voltage circuit inactive in HOLD or HALT mode.
- When the reference voltage circuit is activated, the current drain increases by approximately 100µA compared with when the reference voltage circuit is inactive.

Circuit example 1: When V_{DD}1=V_{DD}2=3.3V

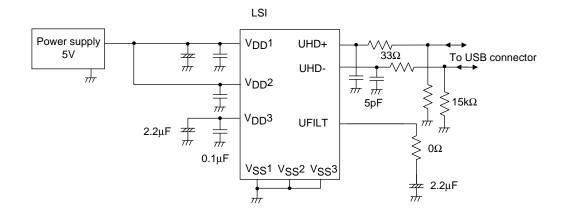
- Inactivating the reference voltage circuit (selection (4)).
- Connecting V_{DD}3 to V_{DD}1 and V_{DD}2.



*1: Needs adjustment on target board.

Circuit example 2: When V_{DD}1=V_{DD}2=5.0V

- Activating the reference voltage circuit (selection (1)).
- Isolating Vpp3 from Vpp1 and Vpp2, and connecting capacitor between Vpp3 and Vss.



Absolute Maximum Ratings at Ta = 25°C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	Specifi typ	cation max	unit
Ма	ximum supply	V _{DD} max	V _{DD} 1, V _{DD} 2, V _{DD} 3	V _{DD} 1= V _{DD} 2= V _{DD} 3	. ↑DD[↓]	-0.3	אני	+6.5	uiiii
Maximum supply voltage Input voltage						-0.3		+0.5	
Input voltage		V _I (1)	XT1, CF1			-0.3		V _{DD} +0.3	V
	ut/output tage	V _{IO} (1)	Ports 0, 1, 2, 3, 7 PWM0, PWM1 XT2			-0.3		V _{DD} +0.3	
	Peak output current	IOPH(1)	Ports 0, 1, 2	When CMOS output type is selected		-10			
		IOPH(2)	PWM0, PWM1	Per 1 applicable pin Per 1 applicable pin		-20			
			Port 3			-20			
		IOPH(3)	P71 to P73	When CMOS output type is selected Per 1 applies blooping		-5			
ınt	Average output current	IOMH(1)	Ports 0, 1, 2	Per 1 applicable pin When CMOS output type is selected		-7.5			
urre	(Note 1-1)			Per 1 applicable pin					
but c		IOMH(2)	PWM0, PWM1	Per 1 applicable pin		-15			
High level output current		IOMH(3)	Port 3 P71 to P73	When CMOS output type is selected Per 1 applicable pin		-3			
High	Total output	ΣΙΟΑΗ(1)	Ports 0, 2	Total current of all applicable pins		-25			
		ΣΙΟΑΗ(2)	Port 1 PWM0, PWM1	Total current of all applicable pins		-25			
		ΣΙΟΑΗ(3)	Ports 0, 1, 2 PWM0, PWM1	Total current of all applicable pins		-45			
		ΣΙΟΑΗ(4)	Port 3 P71 to P73	Total current of all applicable pins		-10			
		ΣΙΟΑΗ(5)	UHD+, UHD-	Total current of all applicable pins		-25			mA
	Peak output current	IOPL(1)	P02 to P07 Ports 1, 2 PWM0, PWM1	Per 1 applicable pin				20	
		IOPL(2)	P00, P01	Per 1 applicable pin				30	
		IOPL(3)	Ports 3, 7 XT2	Per 1 applicable pin				10	
ent	Average output current	IOML(1)	P02 to P07 Ports 1, 2	Per 1 applicable pin				15	
curre	(Note 1-1)	IOML(2)	PWM0, PWM1 P00, P01	Per 1 applicable pin				20	
Low level output current		IOML(3)	Ports 3, 7 XT2	Per 1 applicable pin				7.5	
ow leve	Total output	ΣIOAL(1)	Ports 0, 2	Total current of all applicable pins				45	
_		ΣIOAL(2)	Port 1 PWM0, PWM1	Total current of all applicable pins				45	
		ΣIOAL(3)	Ports 0, 1, 2 PWM0, PWM1	Total current of all applicable pins				80	
		ΣIOAL(4)	Ports 3, 7 XT2	Total current of all applicable pins				15	
		ΣIOAL(5)	UHD+, UHD-	Total current of all applicable pins				25	
	owable power sipation	Pd max	SQFP48(7×7)	Ta=-40 to +85°C				140	mW
Ор	erating ambient	Topr				-40		+85	۰.0
	rage ambient	Tstg				-55		+125	°C

Note 1-1: The average output current is an average of current values measured over 100ms intervals.

Allowable Operating Conditions at Ta = -40 °C to +85 °C, $V_SS1 = V_SS2 = V_SS3 = 0V$

	0 1 1	D' / D	0 - 177			Specific	ation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Operating	V _{DD} (1)	$V_{DD}1=V_{DD}2=V_{DD}3$	0.245μs ≤ tCYC ≤ 200μs		3.0		5.5	
supply voltage (Note 2-1)			0.490μs ≤ tCYC ≤ 200μs Except in onboard programming mode		2.7		5.5	
Memory sustaining supply voltage	VHD	V _{DD} 1=V _{DD} 2=V _{DD} 3	RAM and register contents sustained in HOLD mode.		2.0		5.5	
High level input voltage	V _{IH} (1)	Ports 0, 1, 2, 3 P71 to P73 P70 port input/ interrupt side PWM0, PWM1		2.7 to 5.5	0.3V _{DD} +0.7		V _{DD}	
	V _{IH} (2)	Port 70 watchdog timer side		2.7 to 5.5	0.9V _{DD}		V _{DD}	
	V _{IH} (3)	XT1, XT2, CF1, RES		2.7 to 5.5	0.75V _{DD}		V_{DD}	V
Low level input voltage	V _{IL} (1)	Ports 1, 2, 3 P71 to P73		4.0 to 5.5	V _{SS}		0.1V _{DD} +0.4	
	V _{IL} (2)	P70 port input/ interrupt side		2.7 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (3)	Port 0 PWM0, PWM1		4.0 to 5.5	V _{SS}		0.15V _{DD} +0.4	
	V _{IL} (4)			2.7 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (5)	Port 70 watchdog timer side		2.7 to 5.5	V _{SS}		0.8V _{DD} -1.0	
	V _{IL} (6)	XT1, XT2, CF1, RES		2.7 to 5.5	V _{SS}		0.25V _{DD}	
Instruction	tCYC			3.0 to 5.5	0.245		200	
cycle time (Note 2-2)			Except in onboard programming mode	2.7 to 5.5	0.490		200	μs
External system clock frequency	FEXCF(1)	CF1	CF2 pin open System clock frequency division ratio=1/1 External system clock duty =50±5%	3.0 to 5.5	0.1		12	
			CF2 pin open System clock frequency division ratio=1/1 External system clock duty =50±5%	2.7 to 5.5	0.1		6	MHz
Oscillation frequency	FmCF(1)	CF1, CF2	When 12MHz ceramic oscillation See Fig. 1.	3.0 to 5.5		12		
range (Note 2-3)	FmCF(2)	CF1, CF2	When 6MHz ceramic oscillation See Fig. 1.	2.7 to 5.5		6		MHz
·	FmRC		Internal RC oscillation	2.7 to 5.5	0.3	1.0	2.0	
	FsX'tal	XT1, XT2	32.768kHz crystal oscillation See Fig. 2.	2.7 to 5.5		32.768		kHz

Note 2-1: V_{DD} must be held greater than or equal to 3.0V in the flash ROM onboard programming mode.

Note 2-3: See oscillation characteristics examples.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

Electrical Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Parameter	Symbol	Pin/Remarks	Conditions			Specifica	ition	
Faiametei	Symbol	Fill/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High level input current	l _{IH} (1)	Ports 0, 1, 2, 3 Port 7 RES PWM0, PWM1 UHD+, UHD-	Output disabled Pull-up resistor off VIN=VDD (Including output Tr's off leakage current)	2.7 to 5.5			1	
	I _{IH} (2)	XT1, XT2	Input port configuration VIN=VDD	2.7 to 5.5			1	
	I _{IH} (3)	CF1	V _{IN} =V _{DD}	2.7 to 5.5			15	
Low level input current	I _{IL} (1)	Ports 0, 1, 2, 3 Port 7 RES PWM0, PWM1 UHD+, UHD-	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	2.7 to 5.5	-1			μΑ
	I _{IL} (2)	XT1, XT2	Input port configuration VIN=VSS	2.7 to 5.5	-1			
	I _{IL} (3)	CF1	V _{IN} =V _{SS}	2.7 to 5.5	-15			
High level output	V _{OH} (1)	Ports 0, 1, 2, 3	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
voltage	V _{OH} (2)	P71 to P73	I _{OH} =-0.4mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (3)		I _{OH} =-0.2mA	2.7 to 5.5	V _{DD} -0.4			
	V _{OH} (4)	PWM0, PWM1	I _{OH} =-10mA	4.5 to 5.5	V _{DD} -1.5			
	V _{OH} (5)	P05 to P07	I _{OH} =-1.6mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (6)	(Note 3-1)	I _{OH} =-1mA	2.7 to 5.5	V _{DD} -0.4			
Low level output	V _{OL} (1)	P00, P01	I _{OL} =30mA	4.5 to 5.5			1.5	V
voltage	V _{OL} (2)		I _{OL} =5mA	3.0 to 5.5			0.4	V
	V _{OL} (3)		I _{OL} =2.5mA	2.7 to 5.5			0.4	
	V _{OL} (4)	Ports 0, 1, 2	I _{OL} =10mA	4.5 to 5.5			1.5	
	V _{OL} (5)	PWM0, PWM1	I _{OL} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (6)	XT2	I _{OL} =1mA	2.7 to 5.5			0.4	
	V _{OL} (7)	Ports 3, 7	I _{OL} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (8)		I _{OL} =1mA	2.7 to 5.5			0.4	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2, 3	V _{OH} =0.9V _{DD}	4.5 to 5.5	15	35	80	
	Rpu(2)	Port 7		2.7 to 4.5	18	50	150	kΩ
Hysteresis voltage	VHYS	RES Port 1, 2, 3, 7		2.7 to 5.5		0.1V _{DD}		V
Pin capacitance	СР	All pins	For pins other than that under test: VIN=VSS f=1MHz Ta=25°C	2.7 to 5.5		10		pF

Note 3-1: When the CKO system clock output function (P05) or audio interface output function (P05 to P07) is used.

Serial I/O Characteristics at Ta = -40 °C to +85 °C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0$ V

1. SIO0 Serial I/O Characteristics (Note 4-1-1)

Frequency ISCKL(1) SCK0(P12) See Fig. 9.		_	\	O. make al	Pin/	O and distance			Spec	ification	
Low level ISCKL(1)		-	'arameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Low level pulse width High level pulse width High level pulse width High level pulse width ISCKHA(1a)			Frequency	tSCK(1)	SCK0(P12)	See Fig. 9.		2			
Prequency ISCKHA(1a) ISCKHA(1b) ISCKHA(1b) ISCKHA(1b) ISCKHA(1b) ISCKHA(1b) ISCKHA(1b) ISCKHA(1b) ISCKHA(1b) ISCKHA(1b) ISCKHA(1c) ISCK			Laurianal	+COKL (4)				_			
High level pulse width ISCKH4(1a)				ISCRL(1)				1			
SCKHA(1a) SCKHA(1b) Continuous data transfer mode USB, AIF, SIOA, SIOB, and DMCOPY not used at the same time. See Fig. 9. (Note 4-1:2) Continuous data transfer mode USB, AIF, SIOA, SIOB, and DMCOPY not used at the same time. See Fig. 9. (Note 4-1:2) SCKHA(1c)			•	tSCKH(1)				4			
Suspect Susp			pulse width					'			
SCKHA(1b) DMCOPY not used at the same time. See Fig. 9.				tSCKHA(1a)							
See Fig. 9. 1/2 1/											
SCKHA(tb) SCKHA(tb) SCKHA(tb) SCKHA(tb) SCKHA(tb) SCKHA(tb) SCKHA(tc) SCKH								4			
Sust used at the same time. A.IF, SIO4, SIO9, and DMCOPY not used at the same time. See Fig. 9.		쓩				• See Fig. 9.					
Sust used at the same time. A.IF, SIO4, SIO9, and DMCOPY not used at the same time. See Fig. 9.		r clo				·	2.7 to 5.5				
AIF, SIO4, SIO9, and DMCOPY not used at the same time. See Fig. 9.		Inpu		tSCKHA(1b)							tCYC
SCKHA(1c) SCKH											
Continuous data transfer mode USC KH2 ESC KH2								7			
Continuous data transfer mode USB, AIF, SIO4, SIO9, and DMCOPY used at the same time. See Fig. 9.						• See Fig. 9.					
Substance Subs						·					
DMCOPY used at the same time. 9				tSCKHA(1c)							
Trequency tSCK(2) SCK0(P12) When cMOS output type is selected See Fig. 9.											
Frequency tSCK(2) SCK0(P12) When CMOS output type is selected See Fig. 9. 1/2 tSCK								9			
1/2 1/2						• See Fig. 9.					
1/2 1/2	8 K					·					
1/2 1/2	ial C		Frequency	tSCK(2)	SCK0(P12)			4/3			
Pulse width High level pulse width High level pulse width SCKH(2)	Ser		Low level	tSCKL(2)							
High level pulse width tSCKH(2) tSCKH(2) tSCKHA(2a) tSCKHA(2a) tSCKHA(2a) tSCKHA(2a) tSCKHA(2a) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2b) tSCKHA(2c)				(=)		, and the second			1/2		+00K
Continuous data transfer mode **USB, AIF, SIO4, SIO9, and DMCOPY not used at the same time.** **SCKHA(2b)** **ISCKHA(2b)** **ISCKHA(2c)** **ISCKHA(2c)*			High level	tSCKH(2)					1/2		ISCK
USB, AIF, SIO4, SIO9, and DMCOPY not used at the same time. When CMOS output type is selected See Fig. 9. Continuous data transfer mode USB used at the same time. AIF, SIO4, SIO9, and DMCOPY not used at the same time. When CMOS output type is selected. See Fig. 9. USCKH(2) +2tCYC SCKH(2) +2tCYC USCKH(2) +2tCYC			pulse width						.,_	<u> </u>	
DMCOPY not used at the same time. • When CMOS output type is selected • See Fig. 9. • Continuous data transfer mode • USB used at the same time. • When CMOS output type is selected. • See Fig.9. • Continuous data transfer mode • USB used at the same time. • When CMOS output type is selected. • See Fig.9. • Continuous data transfer mode • USB, AIF, SIO4, SIO9, and DMCOPY not used at the same time. • When CMOS output type is selected. • See Fig.9. • Continuous data transfer mode • USB, AIF, SIO4, SIO9, and DMCOPY used at the same time • When CMOS output type is selected. • See Fig.9. • Continuous data transfer mode • USB, AIF, SIO4, SIO9, and DMCOPY used at the same time • When CMOS output type is selected				tSCKHA(2a)							
time. • When CMOS output type is selected • See Fig. 9. • Continuous data transfer mode • USB used at the same time. • When CMOS output type is selected. • See Fig. 9. • Continuous data transfer mode • USB used at the same time. • AIF, SIO4, SIO9, and DMCOPY not used at the same time. • When CMOS output type is selected. • See Fig. 9. • Continuous data transfer mode • USB, AIF, SIO4, SIO9, and DMCOPY used at the same time • When CMOS output type is selected. • See Fig. 9. • Continuous data transfer mode • USB, AIF, SIO4, SIO9, and DMCOPY used at the same time • When CMOS output type is selected										tSCKH(2)	
When CMOS output type is selected **See Fig. 9. **Continuous data transfer mode **USB used at the same time. **AIF, SIO4, SIO9, and DMCOPY not used at the same time. **When CMOS output type is selected. **See Fig.9.** **ISCKH(2) +2tCYC **ISCKH(2) +						time.				+	
AIF, SIO4, SIO9, and DMCOPY not used at the same time. When CMOS output type is selected. See Fig.9. Continuous data transfer mode USB, AIF, SIO4, SIO9, and DMCOPY used at the same time When CMOS output type is SCKH(2) +2tCYC tSCKH(2) +2tCYC tSCKH(2) +2tCYC tSCKH(2) +2tCYC tSCKH(2) +2tCYC tSCKH(2) +2tCYC selected								+21010		(10/3)tCYC	
AIF, SIO4, SIO9, and DMCOPY not used at the same time. When CMOS output type is selected. See Fig.9. Continuous data transfer mode USB, AIF, SIO4, SIO9, and DMCOPY used at the same time When CMOS output type is SCKH(2) +2tCYC tSCKH(2) +2tCYC tSCKH(2) +2tCYC tSCKH(2) +2tCYC tSCKH(2) +2tCYC tSCKH(2) +2tCYC selected		Slock									
AIF, SIO4, SIO9, and DMCOPY not used at the same time. When CMOS output type is selected. See Fig.9. tSCKH(2) +2tCYC tSCKH(2) + (19/3)tCYC tCYC tSCKH(2) + (19/3)tCYC tCYC tSCKH(2) + (19/3)tCYC tSCKH(2) + (19/3)tCYC tCYC tSCKH(2) + (19/3)tCYC		put 0		tSCKHA(2h)			2.7 to 5.5				
not used at the same time. • When CMOS output type is selected. • See Fig.9. • Continuous data transfer mode • USB, AIF, SIO4, SIO9, and DMCOPY used at the same time • When CMOS output type is selected • When CMOS output type is selected		Out		10011111(20)							
not used at the same time. • When CMOS output type is selected. • See Fig.9. • Continuous data transfer mode • USB, AIF, SIO4, SIO9, and DMCOPY used at the same time • When CMOS output type is selected **SCKH(2)** **CKH(2)** **CKH(2)** **CSCKH(2)** **CSCKH(2)* **CSCK						AIF, SIO4, SIO9, and DMCOPY		+SCKH(2)		tSCKH(2)	tCYC
selected. • See Fig.9. • Continuous data transfer mode • USB, AIF, SIO4, SIO9, and DMCOPY used at the same time • When CMOS output type is selected selected tSCKH(2) +2tCYC (25/3)tCYC											1010
See Fig.9. Continuous data transfer mode USB, AIF, SIO4, SIO9, and DMCOPY used at the same time When CMOS output type is selected See Fig.9. tSCKH(2) tSCKH(2) tSCKH(2) tSCKH(2) tSCKH(2) tSCKH(2)										(19/3)tCYC	
Continuous data transfer mode USB, AIF, SIO4, SIO9, and DMCOPY used at the same time When CMOS output type is selected SCKH(2) +2tCYC Selected											
DMCOPY used at the same time • When CMOS output type is selected tSCKH(2) +2tCYC (25/3)tCYC				tSCKHA(2c)							
DMCOPY used at the same time When CMOS output type is selected Compared to the same time tSCKH(2) +2tCYC +2tCYC (25/3)tCYC						• USB, AIF, SIO4, SIO9, and				tSCKH(2)	
selected (25/3)tCYC										+	
								+2tCYC		(25/3)tCYC	
						• See Fig.9.					

Note 4-1-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.

Note 4-1-2: In an application where the serial clock input is to be used in the continuous data transfer mode, the time from SI0RUN being set when serial clock is high to the falling edge of the first serial clock must be longer than tSCKHA.

Continued from preceding page.

		Parameter	Symbol	Pin/	Conditions			Spec	ification	
		rarameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Serial input	Data setup time		tsDI(1)	SB0(P11), SI0(P11)	Must be specified with respect to rising edge of SIOCLK. See Fig. 9.	0.74- 5.5	0.03			
Serial	Da	ta hold time	thDI(1)			2.7 to 5.5	0.03			
	Input clock	Output delay time	tdDO(1)	SO0(P10), SB0(P11)	Continuous data transfer mode (Note 4-1-3)				(1/3)tCY C +0.05	μs
Serial output	Input		tdDO(2)		• Synchronous 8-bit mode • (Note 4-1-3)	2.7 to 5.5			1tCYC +0.05	
Serie	Output clock		tdDO(3)		(Note 4-1-3)				(1/3)tCY C +0.05	

Note 4-1-3: Must be specified with respect to falling edge of SIOCLK.

Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 9.

2. SIO1 Serial I/O Characteristics (Note 4-2-1)

		D	0	Pin/	Conditions			Spec	ification	
		Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	×	Frequency	tSCK(3)	SCK1(P15)	See Fig. 9.		2			
	Input clock	Low level pulse width	tSCKL(3)			2.7 to 5.5	1			.0.40
Serial clock	In	High level pulse width	tSCKH(3)				1			tCYC
Serial	ock	Frequency	tSCK(4)	SCK1(P15)	When CMOS output type is selected		2			
	S Output clock	Low level pulse width	tSCKL(4)	• See Fig. 9.	2.7 to 5.5		1/2		tSCK	
		High level pulse width	tSCKH(4)					1/2		ISCK
Serial input	Da	ata setup time	tsDI(2)	SB1(P14), SI1(P14)	Must be specified with respect to rising edge of SIOCLK. See Fig. 9.	0.7.	0.03			
Serial	Da	ata hold time	thDI(2)			2.7 to 5.5	0.03			
Serial output	· · · · · ·		tdDO(4)	SO1(P13), SB1(P14)	Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 9.	2.7 to 5.5			(1/3)tCYC +0.05	μѕ

Note 4-2-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.

3. SIO4 Serial I/O Characteristics (Note 4-3-1)

Frequency tSCK(5) SCK4(P24) See Fig. 9. 2	unit
Low level pulse width High level pulse width tSCKH(5) tSCKHA(5a) tSCKHA(5a) tSCKHA(5b) tSCKHA(5b)	
Low level pulse width High level pulse width • USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. • See Fig. 9. • (Note 4-3-2) • USB used at the same time • SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time.	
pulse width High level pulse width tSCKHA(5a) • USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. • See Fig. 9. • (Note 4-3-2) • USB used at the same time • SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time • SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time.	
High level pulse width tSCKHA(5a) • USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. • See Fig. 9. • (Note 4-3-2) • USB used at the same time • SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time • SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time.	
pulse width tSCKHA(5a) • USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. • See Fig. 9. • (Note 4-3-2) • USB used at the same time • SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time.	_
mode, AIF, SIO9, and DMCOPY not used at the same time. • See Fig. 9. • (Note 4-3-2) • USB used at the same time • SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. 7	
not used at the same time. • See Fig. 9. • (Note 4-3-2) • USB used at the same time • SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time.	
See Fig. 9. • (Note 4-3-2) • USB used at the same time • SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time.	
• (Note 4-3-2) • USB used at the same time • SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time.	-
AIF, SIO9, and DMCOPY not used at the same time.	\dashv
AIF, SIO9, and DMCOPY not used at the same time.	
AIF, SIO9, and DMCOPY not used at the same time.	tCYC
used at the same time.	
• See Fig. 9.	
• (Note 4-3-2)	
tSCKHA(5c) • USB, SIO0 continuous transfer	
mode, SIO9, and DMCOPY used	
at the same time. • AIF not used at the same time.	
• See Fig. 9.	
• (Note 4-3-2)	
Frequency tSCK(6) SCK4(P24) • When CMOS output type is selected. Low level tSCKL(6) • See Fig. 9.	
selected.	
pulse width	tSCK
High level tSCKH(6)	
pulse width (Note 4-3-3) tSCKHA(6a) • USB, SIO0 continuous transfer	_
mode AIF SIQ9 and DMCQPY	
not used at the same time.)
• When CMOS output type is + (5/0)/CVC (40/0)/W	<u> </u>
selected. (5/3)tCYC (10/3)tC	,
See Fig. 9. USB used at the same time. SIO0 continuous transfer mode, ALE SIO9 and DMCOPY not tSCKH(6) tSCKH(6) tSCKH(6).	_
tSCKHA(6b) • USB used at the same time.	
• SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not tSCKH(6) tSCKH	
used at the same time.	_
◆ When CMOS output type is (5/3)tCYC (19/3)tC	tCYC
selected.	
• See Fig. 9.	
tSCKHA(6c) • USB, SIO0 continuous transfer	
mode, SIO9, and DMCOPY used	
at the same time. tSCKH(6) tSCKH)
AIF not used at the same time. When CMOS output type is (5/3)tCYC (34/3)tC	<u> </u>
When CMOS output type is selected. (5/3)tCYC (34/3)tC	'
• See Fig. 9.	1

- Note 4-3-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.
- Note 4-3-2: In an application where the serial clock input is to be used in the continuous data transfer mode, the period from the time SI4RUN is set with the serial clock set high to the falling edge of the first serial clock must be longer than tSCKHA.
- Note 4-3-3: When using the serial clock output, make sure that the load at the SCK4 (P24) pin meets the following conditions:
 - Clock rise time tSCKR $< 0.037\mu s$ (see Figure 12.) at Ta=+25°C, V_{DD}=3.3V

Continued from preceding page.

	Parameter	Symbol	Pin/	Pin/ Conditions r		Specification			
	Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
input	Data setup time	tsDI(3)	SO4(P22), SI4(P23)	Must be specified with respect to rising edge of SIOCLK. See Fig. 9	0.7.1.5.5	0.03			
Serial	Data hold time	thDI(3)			2.7 to 5.5	0.03			
Serial output	Output delay time	tdDO(5)	SO4(P22), SI4(P23)	Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 9.	2.7 to 5.5			(1/3)tCYC +0.05	μs

4. SIO9 Serial I/O Characteristics (Note 4-4-1)

	Б	Parameter	Symbol	Pin/	Conditions			Specifi	cation	
		rarameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(7)	SCK9(P27)	See Fig. 9.		2			
		Low level pulse width	tSCKL(7)				1			
		High level pulse width	tSCKH(7)				1			
lock	Serial clock Input clock	TOO TOOLS	tSCKHA(7a)		USB, SIO0 continuous transfer mode, AIF, SIO4, and DMCOPY not used at the same time. See Fig. 9. (Note 4-4-2)		4			
Serial c			tSCKHA(7b)		USB used at the same time. SIO0 continuous transfer mode, AIF, SIO4, and DMCOPY not used at the same time. See Fig. 9. (Note 4-4-2)	2.7 to 5.5	7			tCYC
			tSCKHA(7c)		USB, SIO0 continuous transfer mode, SIO4, and DMCOPY used at the same time. AIF not used at the same time. See Fig. 9. (Note 4-4-2)		15			

Note 4-4-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.

Note 4-4-2: In an application where the serial clock input is to be used in the continuous data transfer mode, the period from the time SI9RUN is set with the serial clock set high to the falling edge of the first serial clock must be longer than tSCKHA.

Continued from preceding page.

		a from preceding	Symbol	Pin/	Conditions			Specif	ication	
		arameter	Symbol	Remarks		V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(8)	SCK9(P27)	When CMOS output type is selected.		4/3			tCYC
		Low level pulse width	tSCKL(8)		• See Fig. 9.		1/2			10014
		High level pulse width	tSCKH(8)					1/2		tSCK
*	ck	(Note 4-4-3)	tSCKHA(8a)		USB, SIO0 continuous transfer mode, AIF, SIO4, and DMCOPY not used at the same time. When CMOS output type is selected. See Fig. 9.		tSCKH(8) + (5/3)tCYC		tSCKH(8) + (10/3)tCYC	
Serial clock	Output clo	Output clock	tSCKHA(8b)		USB used at the same time. SIO0 continuous transfer mode, AIF, SIO4, and DMCOPY not used at the same time. When CMOS output type is selected See Fig. 9.	2.7 to 5.5	tSCKH(8) + (5/3)tCYC		tSCKH(8) + (19/3)tCYC	tCYC
			tSCKHA(8c)		USB, SIO0 continuous transfer mode, SIO4, and DMCOPY used at the same time. AIF not used at the same time. When CMOS output type is selected. See Fig. 9.		tSCKH(8) + (5/3)tCYC		tSCKH(8) + (43/3)tCYC	
input	Da	ta setup time	tsDI(4)	SO9(P25), SI9(P26)	Must be specified with respect to rising edge of SIOCLK. See Fig. 9.		0.03			
Serial input	Da	ta hold time	thDI(4)			2.7 to 5.5	0.03			
Serial output	Ou	tput delay time	tdDO(6)	SO9(P25), SI9(P26)	Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode See Fig. 9.	2.7 to 5.5			(1/3)tCYC +0.05	μѕ

Note 4-4-3: When using the serial clock output, make sure that the load at the SCK9 (P27) pin meets the following conditions:

Clock rise time tSCKR < 0.037 μs (see Figure 12.) at Ta=+25 $^{\circ} C,\,V_{\mbox{DD}}\!=\!3.3V$

Pulse Input Conditions at Ta = -40°C to +85°C, $V_SS1 = V_SS2 = V_SS3 = 0V$

Parameter	Symbol	Pin/Remarks	Conditions			Speci	fication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High/low level pulse width	tPIH(1) tPIL(1)	INT0(P70), INT1(P71), INT2(P72), INT4(P20 to P23), INT5(P24 to P27), INT6(P20), INT7(P24)	Interrupt source flag can be set. Event inputs for timer 0 or 1 are enabled.	2.7 to 5.5	1			
	tPIH(2) tPIL(2)	INT3(P73) when noise filter time constant is 1/1	Interrupt source flag can be set.Event inputs for timer 0 are enabled.	2.7 to 5.5	2			tCYC
	tPIH(3) tPIL(3)	INT3(P73) when noise filter time constant is 1/32	Interrupt source flag can be set. Event inputs for timer 0 are enabled.	2.7 to 5.5	64			
	tPIH(4) tPIL(4)	INT3(P73) when noise filter time constant is 1/128	Interrupt source flag can be set.Event inputs for timer 0 are enabled.	2.7 to 5.5	256			
	tPIL(5)	RMIN(P73)	Recognized by the infrared remote control receiver circuit as a signal	2.7 to 5.5	4			RMCK (Note 5-1)
	tPIL(6)	RES	Resetting is enabled.	2.7 to 5.5	200	-		μs

Note 5-1: Represents the period of the reference clock (1 tCYC to 128 tCYC or the source frequency of the subclock) for the infrared remote control receiver circuit.

AD Converter Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Parameter	Cumbal	Din/Domorko	Conditions			Specific	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN0(P00) to		3.0 to 5.5		8		bit
Absolute accuracy	ET	AN7(P07), AN8(P70),	(Note 6-1)	3.0 to 5.5			±1.5	LSB
Conversion time	TCAD	AN9(P71),	AD conversion time=32×tCYC		15.68		97.92	
		AN10(XT1),	(when ADCR2=0) (Note 6-2)	4.5 to 5.5	(tCYC=		(tCYC=	
		AN11(XT2)			0.490µs)		3.06µs)	
					23.52		97.92	
				3.0 to 5.5	(tCYC=		(tCYC=	
					0.735µs)		3.06µs)	
			AD conversion time=64×tCYC		18.82		97.92	μs
			(when ADCR2=1) (Note 6-2)	4.5 to 5.5	(tCYC=		(tCYC=	
					0.294µs)		1.53µs)	
					47.04		97.92	
				3.0 to 5.5	(tCYC=		(tCYC=	
					0.735µs)		1.53µs)	
Analog input voltage range	VAIN			3.0 to 5.5	V _{SS}		V_{DD}	V
Analog port	IAINH		VAIN=V _{DD}	3.0 to 5.5			1	
input current	IAINL]	VAIN=V _{SS}	3.0 to 5.5	-1			μΑ

Note 6-1: The quantization error ($\pm 1/2$ LSB) is excluded from the absolute accuracy.

Note 6-2: The conversion time refers to the period from the time when an instruction for starting a conversion process is issued to the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

Consumption Current Characteristics at Ta = -40 °C to +85 °C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

		Pin/		oe e, + <u>5</u>		Specif	ication	
Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Normal mode consumption current	IDDOP(1)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		11	27	
(Note 7-1)	IDDOP(2)		Internal PLL oscillation stopped Internal RC oscillation stopped USB circuit stopped 1/1 frequency division ratio	3.0 to 3.6		6.2	16	
	IDDOP(3)		FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		16	37	
	IDDOP(4)		Internal PLL oscillation mode active Internal RC oscillation stopped USB circuit active 1/1 frequency division ratio	3.0 to 3.6		8.0	21	mA
	IDDOP(5)		• FmCF=12MHz ceramic oscillation mode	4.5 to 5.5		7.2	17	
	IDDOP(6)		FsX'tal=32.768kHz crystal oscillation mode System clock set to 6MHz side	3.0 to 3.6		4.4	11	
	IDDOP(7)		Internal RC oscillation stopped 1/2 frequency division ratio	2.7 to 3.0		3.6	8.2	
	IDDOP(8)		• FmCF=0Hz (oscillation stopped)	4.5 to 5.5		0.77	3.7	
	IDDOP(9)		FsX'tal=32.768kHz crystal oscillation mode System clock set to internal RC oscillation	3.0 to 3.6		0.43	2.0	
	IDDOP(10)		1/2 frequency division ratio	2.7 to 3.0		0.36	1.6	
	IDDOP(11)		FmCF=0Hz (oscillation stopped) FsX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		47	184	
	IDDOP(12)		System clock set to crystal oscillation side (32.768kHz)	3.0 to 3.6		19	65	μΑ
	IDDOP(13)		Internal RC oscillation stopped 1/2 frequency division ratio	2.7 to 3.0		15	51	
HALT mode consumption current (Note7-1)	IDDHALT(1)		HALT mode FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		4.9	12	
	IDDHALT(2)		Internal PLL oscillation stopped Internal RC oscillation stopped USB circuit stopped 1/1 frequency division ratio	3.0 to 3.6		2.7	6.4	
	IDDHALT(3)		HALT mode FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		9.5	23	
	IDDHALT(4)		Internal PLL oscillation mode active Internal RC oscillation stopped USB circuit active 1/1 frequency division ratio	3.0 to 3.6		4.7	12	mA
	IDDHALT(5)		HALT mode FmCF=12MHz ceramic oscillation mode	4.5 to 5.5		3.0	7.3	
	IDDHALT(6)	•	FsX'tal=32.768kHz crystal oscillation mode System clock set to 6MHz side	3.0 to 3.6		1.6	3.8	
	IDDHALT(7)		Internal RC oscillation stopped 1/2 frequency division ratio	2.7 to 3.0		1.3	2.9	
	IDDHALT(8)	1	• HALT mode	4.5 to 5.5		0.41	2.0	
	IDDHALT(9)	1	FmCF=0Hz (oscillation stopped) FsX'tal=32.768kHz crystal oscillation mode	3.0 to 3.6		0.20	0.95	
	IDDHALT(10)	1	System clock set to internal RC oscillation 1/2 frequency division ratio	2.7 to 3.0		0.17	0.70	
N. 7. 1. 1701	•				•			

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

Continued from preceding page.

Danamatan	Completed	Pin/	Conditions			Specif	ication	
Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
HALT mode consumption	IDDHALT(11)	V _{DD} 1 =V _{DD} 2	HALT mode FmCF=0Hz (oscillation stopped)	4.5 to 5.5		31	132	
current (Note 7-1)	IDDHALT(12)	=V _{DD} 3	FsX'tal=32.768kHz crystal oscillation mode System clock set to crystal oscillation side (32.768kHz)	3.0 to 3.6		9.1	53	
	IDDHALT(13)		Internal RC oscillation stopped 1/2 frequency division ratio	2.7 to 3.0		6.3	42	
HOLD mode	IDDHOLD(1)	V _{DD} 1	HOLD mode	4.5 to 5.5		0.24	72	μΑ
consumption	IDDHOLD(2)		CF1=V _{DD} or open (External clock mode)	3.0 to 3.6		0.12	38	
current	IDDHOLD(3)			2.7 to 3.0		0.11	33	
Timer HOLD	IDDHOLD(4)		Timer HOLD mode	4.5 to 5.5		26	115	
mode	IDDHOLD(5)		CF1=V _{DD} or open (External clock mode)	3.0 to 3.6		6.1	50	
consumption current	IDDHOLD(6)		FsX'tal=32.768kHz crystal oscillation mode	2.7 to 3.0		3.8	40	

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

USB Characteristics and Timing at $Ta = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

	· · · · · · · · · · · · · · · · · · ·	10 0 10 100 0, 1002	, DD-	, 225			
Parameter	Cumbal	Conditions	Specification				
Parameter	Symbol	Conditions	min	min typ max		unit	
High level output	VOH(USB)	• 15kΩ±5% to GND	2.8		3.6	V	
Low level output	VOL(USB)	• 1.5kΩ±5% to 3.6V	0.0		0.3	V	
Output signal crossover voltage	V _{CRS}		1.3		2.0	V	
Differential input sensitivity	V _{DI}	• (UHD+)-(UHD-)	0.2			V	
Differential input common mode range	V _{СМ}		0.8		2.5	V	
High level input	V _{IH(USB)}		2.0			V	
Low level input	V _{IL(USB)}				0.8	V	
USB data rise time	t _R	• R _S =33Ω, C _L =50pF	4		20	ns	
USB data fall time	t _F	• R _S =33Ω, C _L =50pF	4		20	ns	

F-ROM Programming Characteristics at $Ta = +10^{\circ}C$ to $+55^{\circ}C$, VSS1 = VSS2 = VSS3 = 0V

•	_			, ,	~~		<i>-</i>	
Parameter	Cumbal	Pin/	Conditions		Specification			
Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Onboard programming current	IDDFW(1)	V _{DD} 1	Excluding power dissipation in the microcontroller block	3.0 to 5.5		5	10	mA
Programming time	tFW(1)		Erase operation	204-55		20	30	ms
	tFW(2)		Write operation	3.0 to 5.5		40	60	μs

Main System Clock Oscillation

The constant values of the oscillator and oscillation circuit for the main and system clocks must be determined after exercising extensive oscillation evaluation tests. For an application in which the USB host function is to be used, use an oscillator having the accuracy and precision that satisfy the USB specifications.

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized in the following cases (see Figure 4):

- Till the oscillation gets stabilized after VDD goes above the operating voltage lower limit.
- Till the oscillation gets stabilized after the instruction for starting the main clock oscillation circuit is executed.
- Till the oscillation gets stabilized after the HOLD mode is released.
- Till the oscillation gets stabilized after the X'tal HOLD mode is released with CFSTOP (OCR register, bit 0) set to 0.

Subsystem Clock Oscillation

Table 1 shows the characteristics of a sample subsystem clock oscillation circuit that are measured using a SANYO-designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 Characteristics of a Sample subsystem Clock Oscillator Circuit with a Crystal Oscillator

Nominal Frequency	Vendor Name	Oscillator Name	Circuit Constant				Operating		illation ation Time		
			C3 [pF]	C4 [pF]	Rf [Ω]	Rd2 [Ω]	Voltage Range [V]	typ [s]	max [s]	Remarks	
				[bi]	[bi]	[22]	[22]		[9]	[9]	Applicable CL
32.7	768kHz	EPSON TOYOCOM	MC-306	18	18	OPEN	560k	2.7 to 5.0	1.1	3.0	value=12.5pF
										SMD type	

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized in the following cases (see Figure 4):

- Till the oscillation gets stabilized after the instruction for starting the subclock oscillation circuit is executed.
- Till the oscillation gets stabilized after the HOLD mode is released with EXTOSC (OCR register, bit 6) set to 1.

Note: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.

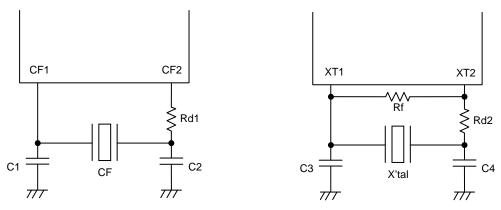
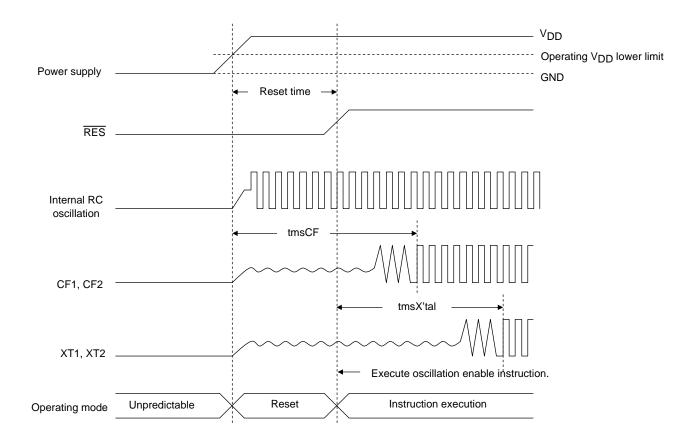


Figure 1 CF Oscillator Circuit

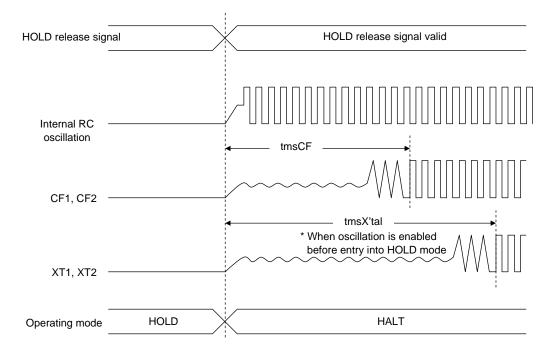
Figure 2 Crystal Oscillator Circuit



Figure 3 AC Timing Measurement Point

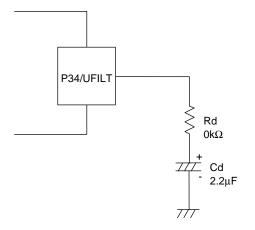


Reset Time and Oscillation Stabilization Time



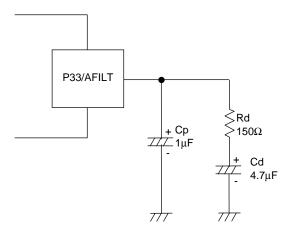
HOLD Release Signal and Oscillation Stabilization Time

Figure 4 Oscillation Stabilization Time



When using the internal PLL circuit to generate the 48MHz clock for USB, it is necessary to connect a filter circuit to the P34/UFILT pin such as that shown in the left figure.

Figure 5 External Filter Circuit for the Internal USB-dedicated PLL Circuit



To generate the master clock for the audio interface using the internal PLL circuit, it is necessary to connect a filter circuit to the P33/AFILT pin that is shown in the left figure.

Figure 6 External Filter Circuit for Audio Interface (Used with Internal PLL Circuit)

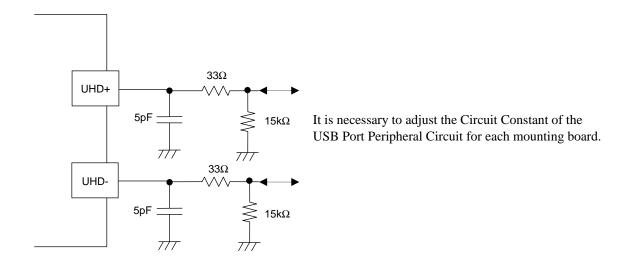
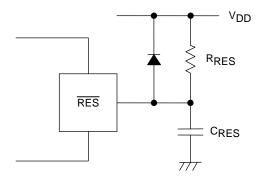


Figure 7 USB Port Peripheral Circuit



Note:

Determine the value of CRES and RRES so that the reset signal is present for a period of 200µs after the supply voltage goes beyond the lower limit of the IC's operating voltage.

Figure 8 Reset Circuit

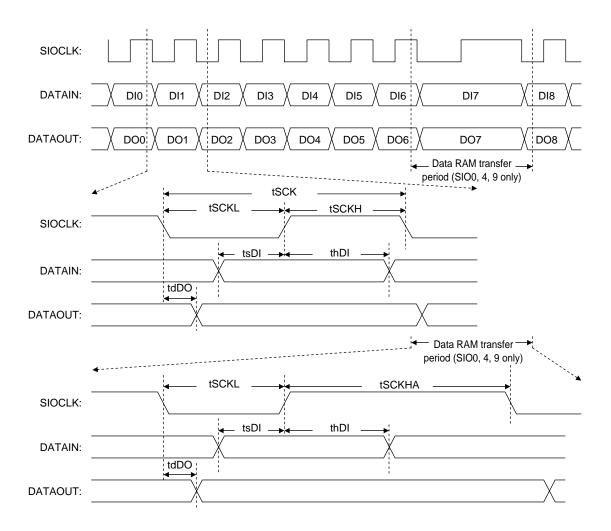


Figure 9 Serial I/O Waveform

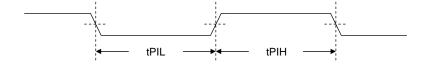


Figure 10 Pulse Input Timing Signal Waveform

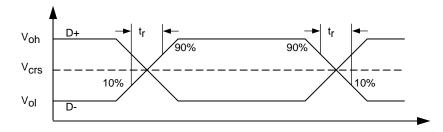
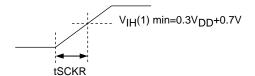


Figure 11 USB Data Signal Timing and Voltage Level



tSCKR:

Defined as the time period from the time the state of the output starts changing till the time it reaches the value of V_{IH}(1).

Figure 12 Serial Clock Output Timing Signal Waveform

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